

Product Summary

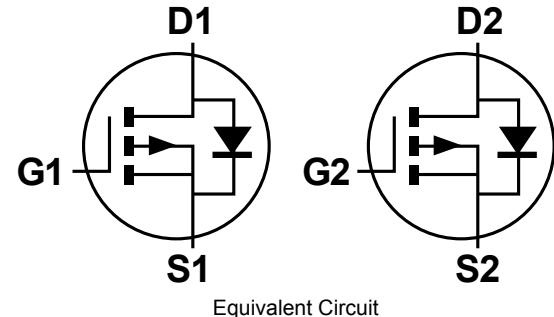
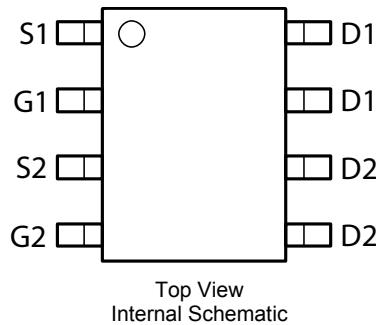
$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	Package	I_D $T_A = +25^\circ C$
-30V	70m Ω @ $V_{GS} = -10V$	SO-8	-3.9A
	95m Ω @ $V_{GS} = -4.5V$		-3.3A

Description

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- Power Management Functions
- DC-DC Converters



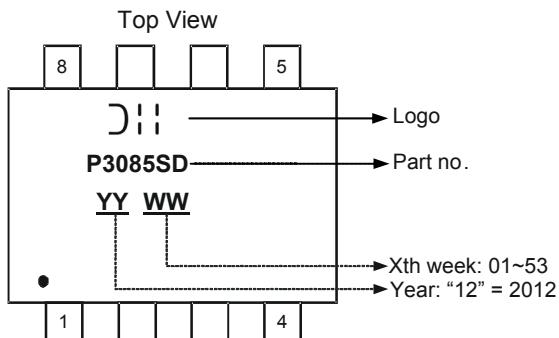
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3085LSD-13	SO-8	2500/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant
2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-30	V
Gate-Source Voltage			V_{GSS}	± 20	V
Continuous Drain Current (Note 6) $V_{GS} = -10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	-3.9 -3.1	A
	$t < 10\text{s}$	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	-4.9 -3.9	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	-2.5	A
Pulsed Drain Current (10 μs pulse, duty cycle = 1%)			I_{DM}	20	A

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	P_D	1.1	W
	$T_A = +70^\circ\text{C}$		0.7	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	107	$^\circ\text{C/W}$
	$t < 10\text{s}$		70	
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	1.7	W
	$T_A = +70^\circ\text{C}$		1.1	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	75	$^\circ\text{C/W}$
	$t < 10\text{s}$		50	
Thermal Resistance, Junction to Case	$R_{\theta JC}$		14.5	
Operating and Storage Temperature Range	T_J, T_{STG}		-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	-30	—	—	V	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1	μA	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(\text{th})}$	-1	—	-3	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	50	70	$\text{m}\Omega$	$V_{GS} = -10\text{V}, I_D = -5.3\text{A}$
		—	75	95		$V_{GS} = -4.5\text{V}, I_D = -4.2\text{A}$
Forward Transfer Admittance	$ Y_{fs} $	—	5.8	—	S	$V_{DS} = -5\text{V}, I_D = -5.3\text{A}$
Diode Forward Voltage	V_{SD}	—	-0.7	-1.2	V	$V_{GS} = 0\text{V}, I_S = -1\text{A}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	563	—	pF	$V_{DS} = -25\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	48	—		
Reverse Transfer Capacitance	C_{rss}	—	41	—		
Gate Resistance	R_G	—	10.3	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Total Gate Charge ($V_{GS} = -4.5\text{V}$)	Q_g	—	5.2	—	nC	$V_{DS} = -15\text{V}, I_D = -3.8\text{A}$
Total Gate Charge ($V_{GS} = -10\text{V}$)	Q_g	—	11	—		
Gate-Source Charge	Q_{gs}	—	1.7	—		
Gate-Drain Charge	Q_{gd}	—	1.9	—		
Turn-On Delay Time	$t_{D(\text{on})}$	—	4.8	—	nS	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -1\text{A}, R_G = 6.0\Omega$
Turn-On Rise Time	t_r	—	5	—		
Turn-Off Delay Time	$t_{D(\text{off})}$	—	31	—		
Turn-Off Fall Time	t_f	—	14.6	—		

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

- 7. I_{AR} and E_{AR} rating are based on low frequency and duty cycles to keep $T_J = 25^\circ\text{C}$.

- 8. Short duration pulse test used to minimize self-heating effect.

- 9. Guaranteed by design. Not subject to product testing.

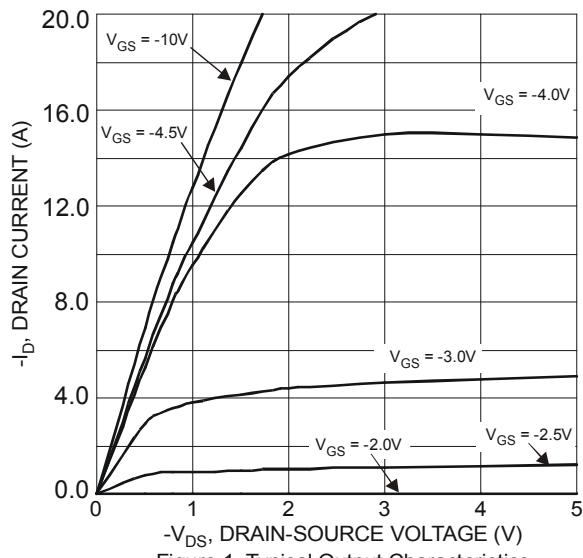


Figure 1 Typical Output Characteristics

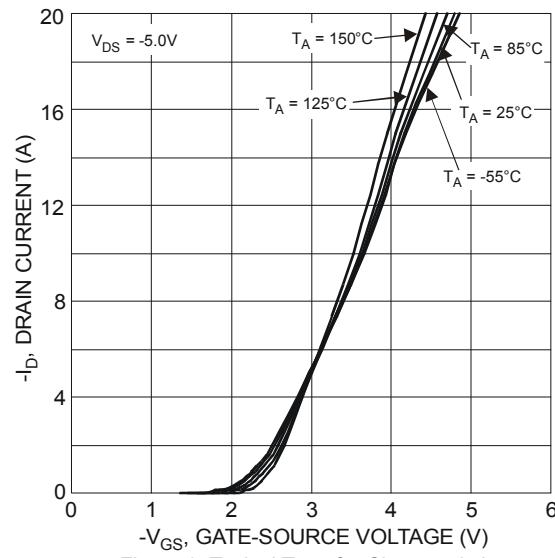


Figure 2 Typical Transfer Characteristics

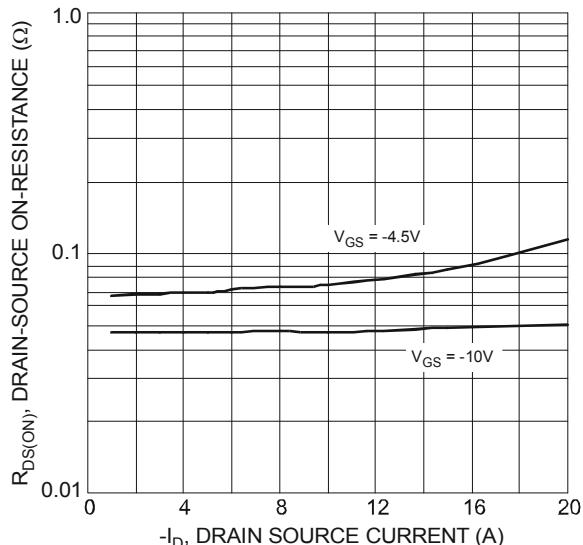


Figure 3 Typical On-Resistance vs.
Drain Current and Gate Voltage

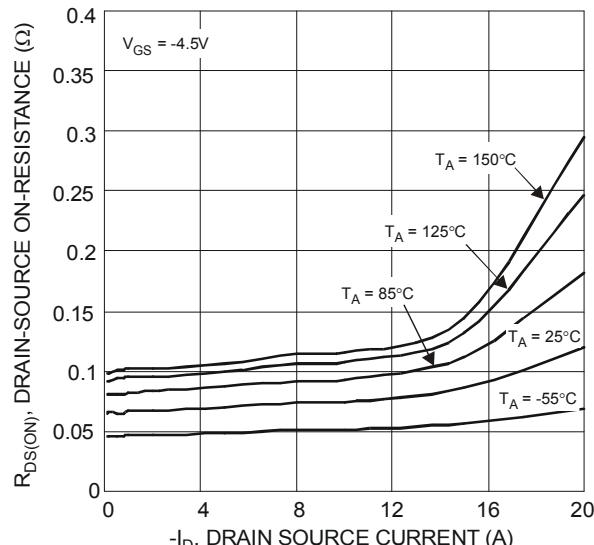


Figure 4 Typical On-Resistance vs.
Drain Current and Temperature

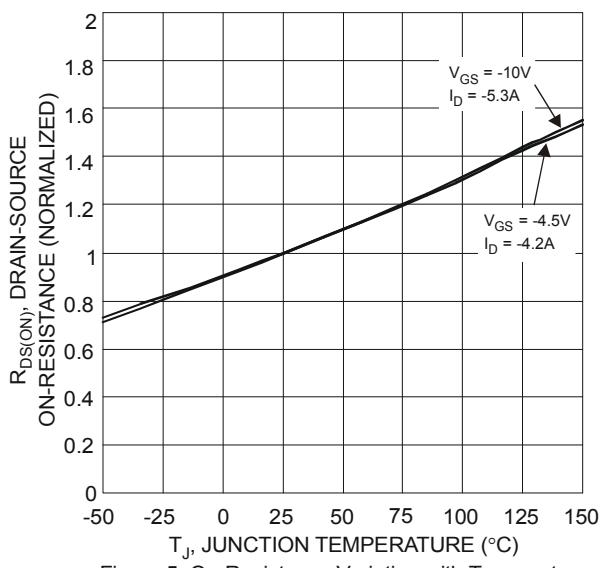


Figure 5 On-Resistance Variation with Temperature

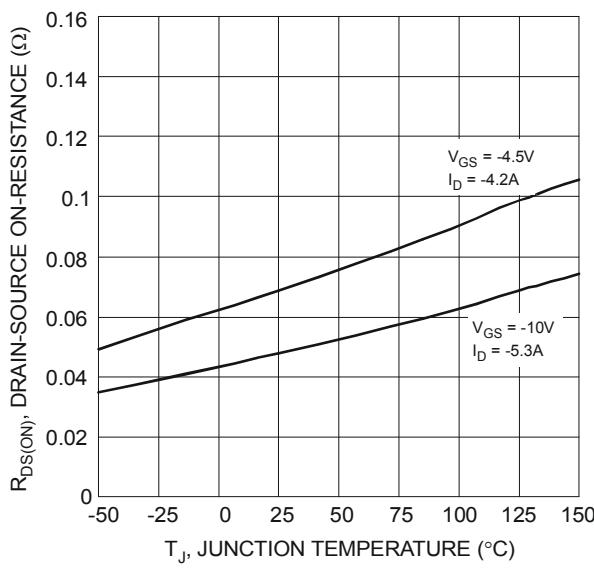


Figure 6 On-Resistance Variation with Temperature

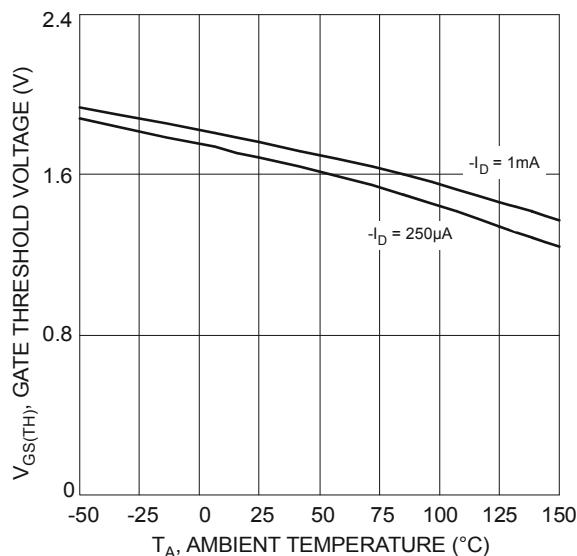


Figure 7 Gate Threshold Variation vs. Ambient Temperature

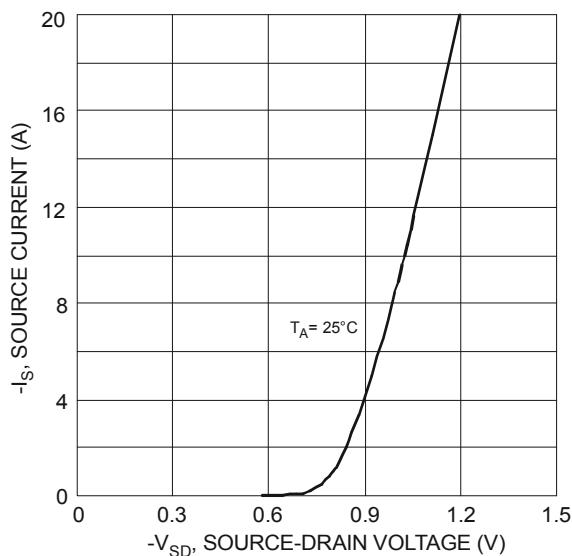


Figure 8 Diode Forward Voltage vs. Current

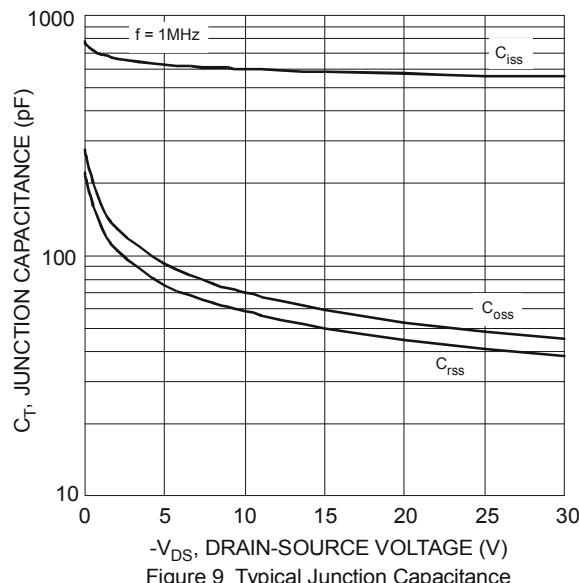


Figure 9 Typical Junction Capacitance

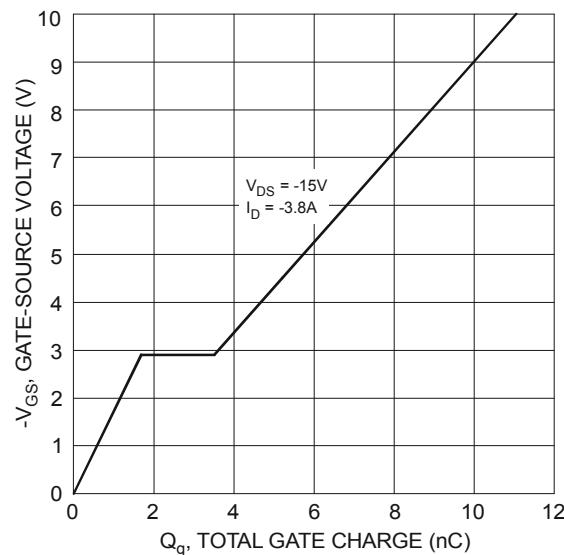
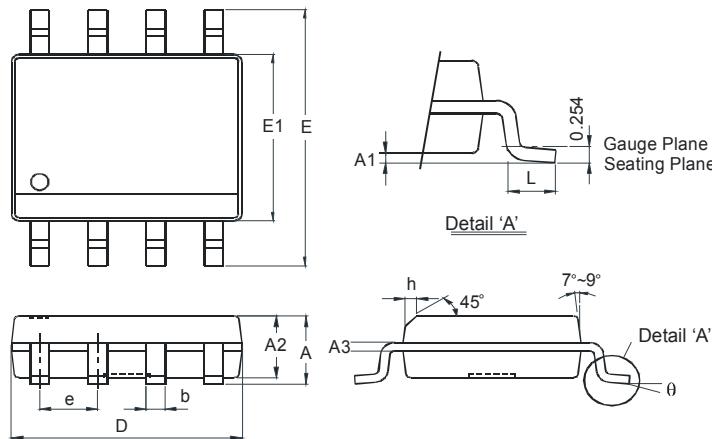


Figure 10 Gate-Charge Characteristics

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

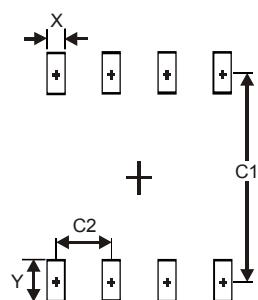


SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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